



Patent
Attorney's Docket No. 016660-055

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Wing Cheung HO et al) Group Art Unit: 1725
Application No.: 09/649,084) Examiner: L. Edmondson
Filed: August 28, 2000)
For: WIRE-BONDING APPARATUS)
WITH IMPROVED XY-TABLE)
ORIENTATION)

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated December 20, 2000, kindly amend the above-identified application as follows:

IN THE CLAIMS:

1. (Amended) Wedge wire bonding apparatus comprising:
 - (a) means for supporting a workpiece,
 - (b) a bonding head including a transducer having a longitudinal axis,
 - (c) means for causing relative movement of the workpiece and the transducer along orthogonal X and Y axes simultaneously, and
 - (d) means for supporting the bonding head above the workpiece such that the longitudinal axis of said transducer lies, at all times during a wire bonding operation, along a line dividing said X and Y axes.